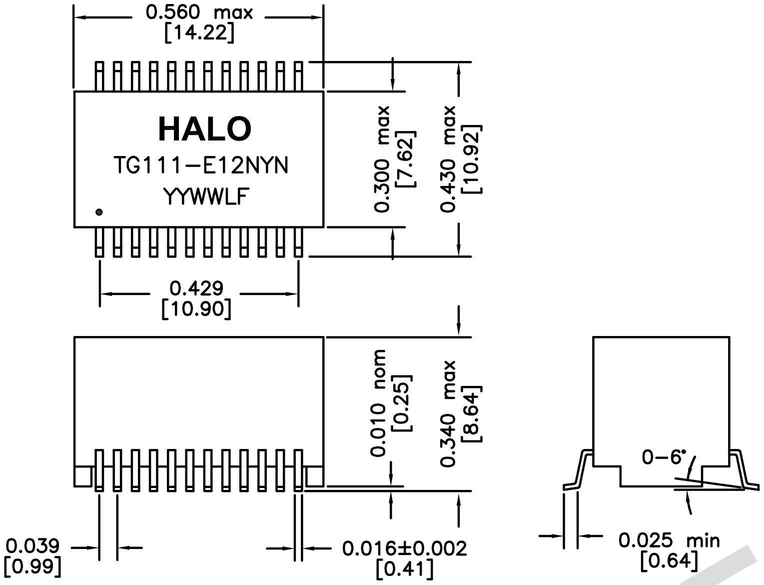
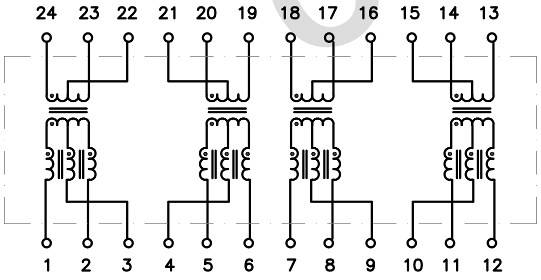
US PATENT NO. 5,656,985 6,297,720B1 6,297,721B1
6,320,489B1 6,344,785B1 6,662,431B1



DIMENSIONS: Inch [mm]
CO–PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



PART NO. : TG111-E12NYNLF

24PIN 0.039" LEAD PITCH SMT PACKAGE

DESIGNED FOR ONE–PORT GIGABIT, IEEE802.3ab OR DUAL–PORT FAST ETHERNET, IEEE802.3u APPLICATIONS

COMPLIANT WITH IEEE802.3af REQUIREMENTS WITH 350mA CURRENT CARRYING CAPACITY FOR PoE

AUTO–MDIX COMPATIBLE

LEAD–FREE/RoHS COMPLIANT, "GREEN PRODUCT"

COMPATIBLE TO LEAD–FREE SOLDERING PROCESS CONDITION PER IPC/JEDEC J–STD–020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE –40/+85°C

ELECTRICAL SPECIFICATIONS @ 25°C

TURNS RATIO	1CT:1CT ±2%
OCL (100KHz,0.1Vrms,8mADC)	350μH min
INSERTION LOSS	
1–100MHz	–1.1dB max
RETURN LOSS	
1–40MHz	–18dB min
60MHz	–14dB min
80MHz	–12dB min
100MHz	–10dB min
CMR	
1–100MHz	–40dB typ
CROSSTALK	
1–30MHz	–50dB typ
60MHz	–45dB typ
100MHz	–40dB typ
ISOLATION	1,500Vrms

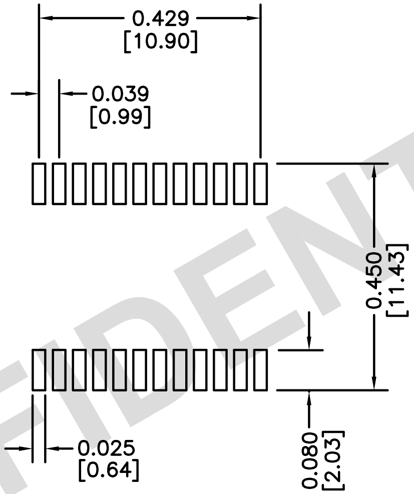
HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE		
FOR	FAST/GIGABIT ETHERNET		
PART NO.	TG111–E12NYNLF		
SCALE	NONE	PAGE	1 OF 2

SIGNATURES		DATE
DRAWN	LI ZHI ZHONG	4/29/11
CHECKED	LEI KEONG	5/17/11
APPROVED	PETER LU	5/17/11
FILE	E12NYNLF.DWG	

REV.	DESC.	DATE
A	FIRST ISSUE	4/29/11
B	PROD. RELEASE	5/17/11



RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE		
FOR	FAST/GIGABIT ETHERNET		
PART NO.	TG111–E12NYNLF		
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